

SID

Factory: Rot am See

Article:

ML4

Provided:

Customer:

Date:

31.03.2026

WURTH
ELEKTRONIK
MORE THAN
YOU EXPECT

Processtechnology: B: undefined

Material Text	Mat. Nr.	µm	Stackup	Process overview
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A-RS Kupferfolie-035my 330x490mm	50200242	35	VS	1		
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	502		2		
A-RAS-FR4-PP-7628-H45-TG150-HF-EM-37B...	50203002	0		3		
A-RAS-FR4-PP-7628-H45-TG150-HF-EM-37B...	50203002	0		4		
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	0		5		
		105	L2			
C-RaS-FR4-ML-0.711mm-105+105-TG150-HF...	50203137	710		6	A00	B00
		105	L3			
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	502		7		
A-RAS-FR4-PP-7628-H45-TG150-HF-EM-37B...	50203002	0		8		
A-RAS-FR4-PP-7628-H45-TG150-HF-EM-37B...	50203002	0		9		
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	0		10		
A-RS Kupferfolie-035my 330x490mm	50200242	35	RS	11		

Thickness after Pressing

B00:

1890 µm

Tol+:

200 µm

Tol-:

200 µm

Dmax:

2090 µm

Dmin:

1690 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

2000 µm

Tol+:

200 µm

Tol-:

200 µm

Dmax:

2200 µm

Dmin:

1800 µm

Measuring point: (05) over SM and galv. Cu; both sides

nominal:

1994 µm

Version 1.2.20.35

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